

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-12. (Canceled)

13. (Currently amended) A ~~dry etching~~ method for producing a solar cell comprising:

placing a substrate ~~to be etched~~ for a solar cell on an RF electrode provided inside a chamber, directly or through a tray;

covering said substrate ~~to be etched~~ with a plate, wherein said plate comprises an obstacle with a plurality of obstacle forming members that inhibit a part of gas and plasma from passing through said plate; and

forming fine ~~fixtures~~ textures on a surface of said substrate ~~to be etched by a reactive ion etching method;~~

~~wherein said plate comprises an obstacle with a plurality of obstacle forming members that inhibit a part of gas and plasma from passing through said plate~~ by using residues being chiefly composed of components of said substrate as an etching mask.

14. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 13, wherein said substrate ~~to be etched~~ is made of silicon.

15. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 13, wherein said plate covers said substrate ~~to be etched~~ while a distance of 5 mm to 30 mm is between the substrate and plate.

16-17. (Canceled)

18. (Currently amended) A ~~dry-etching~~ method for producing a solar cell, comprising:  
placing a substrate ~~to be etched~~ on an RF electrode provided inside a chamber, directly or through a tray;  
covering said substrate ~~to be etched~~ with a plate provided with a number of opening portions; and  
etching the substrate by a reactive ion etching method;  
wherein fine textures are formed on a surface of said substrate ~~to be etched~~ and said plate is cleaned on a surface side concurrently.

19. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 20, wherein said ~~dry-etching method is~~ first substrate is etched by a reactive ion etching method.

20. (Currently amended) A ~~dry etching~~ method for producing a solar cell comprising:

placing a first substrate ~~to be etched for a solar cell~~ on an RF electrode provided inside a chamber, directly or through a tray; ~~and~~

covering said first substrate ~~to be etched~~ with a plate provided with a number of opening portions;

~~wherein forming~~ fine textures ~~are formed~~ on a surface of said first substrate ~~to be etched~~ and cleaning said plate ~~is cleaned~~ on a surface side concurrently,

~~wherein placing~~ a second substrate ~~to be etched next is placed~~ inside ~~a~~ the chamber, with said plate positioned such that ~~a~~ the surface side and a back surface side thereof are being reversed after said plate is cleaned on the surface side, and forming fine textures ~~are formed~~ on a surface of said second substrate ~~to be etched next~~.

21-22. (Canceled)

23. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 13, wherein an opening portion is provided between neighboring obstacle forming members.

24. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 23, wherein an open area ratio of said obstacle is 5 to 40%.

25. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 13, wherein said obstacle forming members are a plurality of long members aligned with a clearance in between.

26. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 25, wherein said long member is a bar-shaped or sheet member.

27. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 13, wherein said obstacle forming member comprises a mesh woven by crossing said plurality of long members over and under with each other.

28. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 13, wherein said obstacle comprises a plurality of obstacles of a stacked structure.

29. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 28, wherein said obstacle comprises a member formed by stacking a plurality of long members aligned with a clearance in between, in different directions.

30. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 13, wherein said obstacle forming member is made of one kind or a combination of two or more kinds selected from a group consisting of materials (a), (b), and (c) as follows:

- (a) a glass-based material;
- (b) a metal material; and
- (c) a resin material.

31. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 30, wherein said metal material is an aluminum-based material.

32. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 18, wherein said plate is structured in such a manner that a surface and a back surface can be reversed.

33. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 32, wherein the surface and the back surface of said plate are of substantially a same shape.

34. (Currently amended) A ~~dry-etching~~ method for forming fine textures on a surface of a substrate to be etched, said dry-etching method producing a solar cell comprising:

placing a substrate ~~to be etched~~ for a solar cell on an RF electrode provided inside a chamber, directly or through a tray;

covering said substrate ~~to be etched~~ with a plate ~~comprising an obstacle that provided with a number of opening portions, wherein said plate~~ inhibits a part of a gas and plasma from passing through said plate; and

~~etching the substrate by a reactive ion etching method;~~

~~wherein a member forming said obstacle is provided with a number of opening portions~~ forming fine textures on a surface of said substrate by using residues being chiefly composed of components of said substrate as an etching mask.

35. (Currently amended) The ~~dry-etching~~ method for producing a solar cell according to Claim 34, wherein an open area ratio of said obstacle is 5 to 40%.

36. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 34, wherein said substrate ~~to be etched~~ is made of silicon.

37. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 34, wherein said plate covers said substrate ~~to be etched~~ while a distance of 5 mm to 30 mm is between the substrate and plate.

38. (Canceled)

39. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 34, wherein said obstacle is made of one kind or a combination of two or more kinds selected from a group consisting of materials (a), (b), and (c) as follows:

- (a) a glass-based material;
- (b) a metal material; and
- (c) a resin material.

40. (Currently amended) The ~~dry etching~~ method for producing a solar cell according to Claim 39, wherein said metal material is an aluminum-based material.

41. (New) The method for producing a solar cell according to Claim 34, wherein said substrate is etched by a reactive ion etching method..